

Part Number: XZFBB53W-8

1.6 x 0.8 mm SMD Chip LED Lamp

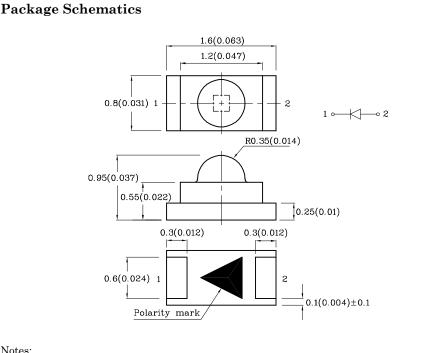
Features

- Ideal for indication light on hand held products
- Long life and robust package
- Standard Package: 2,000pcs/ Reel
- MSL (Moisture Sensitivity Level): 3
- Halogen-free
- RoHS compliant





ATTENTION OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES



Notes: 1. All dimensions are in millimeters (inches).

2. Tolerance is $\pm 0.15(0.006")$ unless otherwise noted.

3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)	Blue (InGaN)	Unit			
Reverse Voltage	rse Voltage V _R		V		
Forward Current	$\mathbf{I}_{\mathbf{F}}$	30	mA		
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	100	mA		
Power Dissipation	\mathbf{P}_{D}	120	mW		
Electrostatic Discharge Threshold (HBM)	250	V			
Operating Temperature	$T_{\rm A}$	$-40 \sim +85$	°C		
Storage Temperature	Tstg	-40 ~ +85	C		

A Relative Humidity between 40% and 60% is recommended in ESD-protected work areas to reduce static build up during assembly process (Reference JEDEC/JESD625-A and JEDEC/J-STD-033)

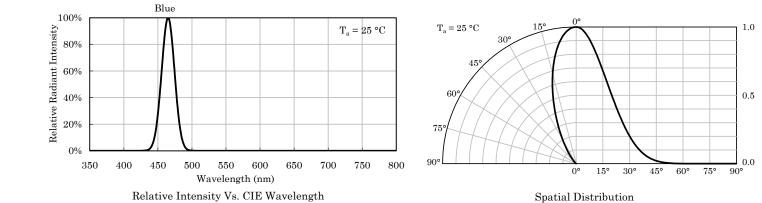
Operating Characteristics (T _A =25°C)	Blue (InGaN)	Unit	
Forward Voltage (Typ.) (I _F =20mA)	V_{F}	3.3	V
Forward Voltage (Max.) (I _F =20mA)	V_{F}	4	V
Reverse Current (Max.) (V _R =5V)	I_R	50	μΑ
Wavelength of Peak Emission CIE127-2007* (Typ.) (I _F =20mA)	λP	465*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) (I _F =20mA)	λD	470*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =20mA)	$\bigtriangleup\lambda$	22	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	100	pF

Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity CIE127-2007* (I _F =20mA) mcd		Wavelength CIE127-2007* nm λP	Viewing Angle 20 1/2
				min.	typ.		
XZFBB53W-8	Blue	InGaN	Water Clear	200*	347*	465*	40°

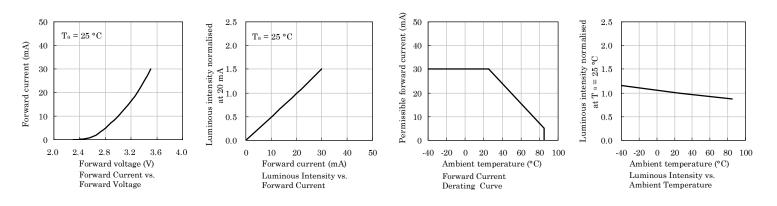
*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.

Feb 27,2023

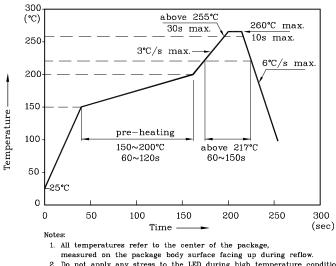




✤ Blue



LED is recommended for reflow soldering and soldering profile is shown below.



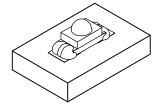
Do not apply any stress to the LED during high temperature conditions. Maximum number of soldering passes: 2 З.

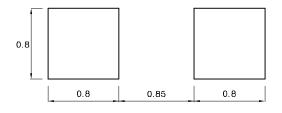
Reflow Soldering Profile for SMD Products (Pb-Free Components)



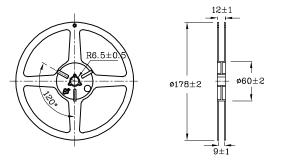
✤ The device has a single mounting surface. The device must be mounted according to the specifications.

Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)

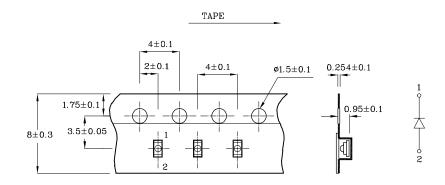




Reel Dimension (Units : mm)



Tape Specification (Units : mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm

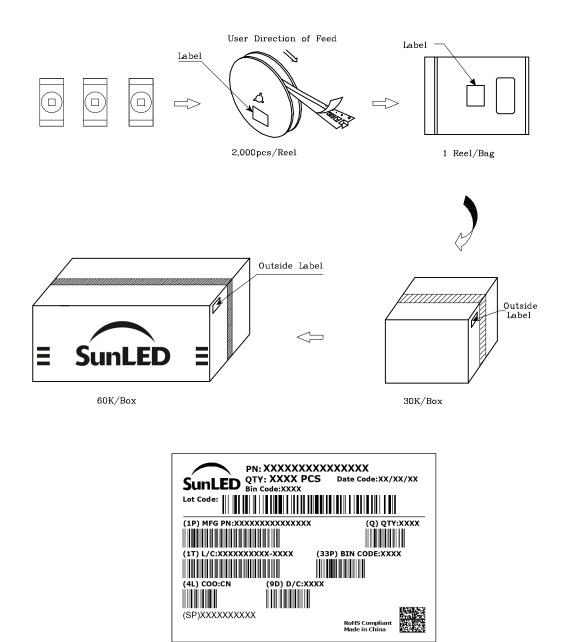
2. Luminous intensity / luminous flux: +/-15%

3. Forward Voltage: +/-0.1V $\,$

Note: Accuracy may depend on the sorting parameters.



PACKING & LABEL SPECIFICATIONS



TERMS OF USE

- 1. Data presented in this document reflect statistical figures and should be treated as technical reference only.
- 2. Contents within this document are subject to improvement and enhancement changes without notice.
- 3. The product(s) in this document are designed to be operated within the electrical and environmental specifications indicated on the datasheet.
- User accepts full risk and responsibility when operating the product(s) beyond their intended specifications.
- 4. The product(s) described in this document are intended for electronic applications in which a person's life is not reliant upon the LED. Please consult with a SunLED representative for special applications where the LED may have a direct impact on a person's life.
- 5. The performance of the product(s) should be evaluated and verified by the customer to ensure it can meet the customer's application requirements.
- 6. The contents within this document may not be altered without prior consent by SunLED.
- 7. Additional technical notes are available at <u>https://www.SunLEDusa.com/TechnicalNotes.asp</u>